



Note:

1. Material:
 - 1.1 Housing: High temperature thermoplastic with g.f. UL94v-0
 - 1.2 Contact: copper alloy, t=0.20mm
 - 1.3 Shell: copper alloy, t=0.25mm
2. Specification:
 - 2.1 Current rating: 1 A Max.
 - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - 2.3 Contact resistance: 50 mΩ Max.
 - 2.4 Insulation resistance: 100 MW Min.
 - 2.5 Total mating force: 3.57 Kgf Max.
 - 2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 10000 insertion/extraction cycles
 - 2.7 Temperature range: -30° C~80° C

RECOMMENDED PCB LAYOUT

HDC 有限公司

设计 DRAW BY	杨帆	审核 DISCUSS BY		图名 DRAWING NO	MICRO USB AB TYPE DIP有柱	图号 SHEET NO	019	日期 DATE	2008.10.30
校对 DISCUSS BY		比例 SCALE	2:1	客户 VERSION		备注 REMARK		版次 REMARK	
					数量 QUAN			张号 SHEET	1/1